









PRODUCT DATASHEET



- ► PCB / CHIP LED
- ► 1206RV (3212) 1.1t
- ► Cool White (7400K)

PRELIMINARY

NOW28S93RV







FEATURES:

Package: PCB / CHIP LED Top View Package

Forward Current: 20mA Forward Voltage (typ.): 2.8V

Luminous Intensity (typ.): 100mcd@5mA

Colour: Cool White

CCT: 7400K

Viewing angle: 140°

Materials:

Die: InGaN

Resin: Epoxy (Yellow Diffused) Operating Temperature: -40~+80°C

Storage Temperature: -40~+85°C

Grouping parameters:

Forward voltage

Luminous intensity

CIE Chromaticity

Soldering methods: Reflow soldering Preconditioning: acc. to JEDEC Level 3

Packing: 8mm tape with 3000/reel, ø180mm (7")

APPLICATIONS:

1206RV 2.5t Series

- Indication Light
- Switch Light
- 3C Application



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	V_R	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	102	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

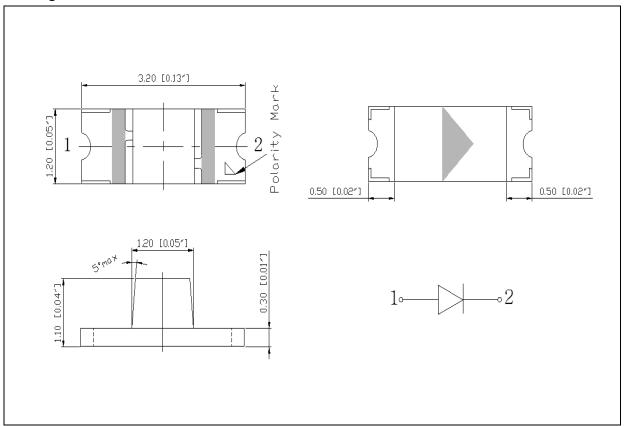
Parameter	Symbol	Values			Unit	Test
Parameter	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	2.5	2.8	3.4	V	I _F =5mA
Luminous Intensity	I _V	63	100	200	mcd	I _F =5mA
Chromaticity	Х		0.3040			I _F =5mA
Coordinates	Y		0.3010			
Colour Temperature	ССТ		7400		К	I _F =5mA
Viewing Angle	2θ _{1/2}		140		deg	I _F =5mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



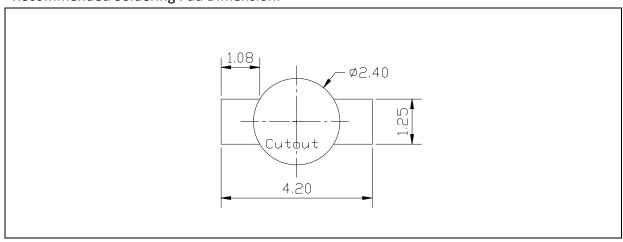
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 5mA$):

Code	Min.	Max.	Unit
F	2.5	3.4	V

Luminous Intensity Classifications ($I_F = 5mA$):

Code	Min.	Max.	Unit
I	63	200	mcd



CIE CHROMATICITY DIAGRAM:

>	
	x

Chromaticity Coordinates Classifications ($I_F = 300 \text{mA}$):

:	1	2	2	3	3	4	4
Х	Υ	Х	Υ	Х	Υ	Х	Υ



ELECTRO-OPTICAL CHARACTERISTICS:

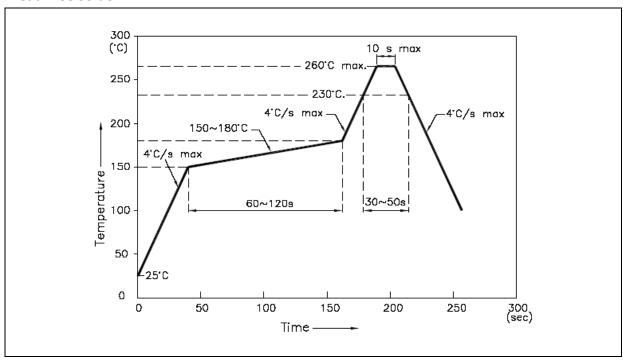
Relative Spectral Distribution	Forward Current v.s. Forward Voltage
Relative Intensity (5mA)	Forward Voltage (V)
Wavelength (nm)	Forward Current (mA)

Directive Radiation	



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



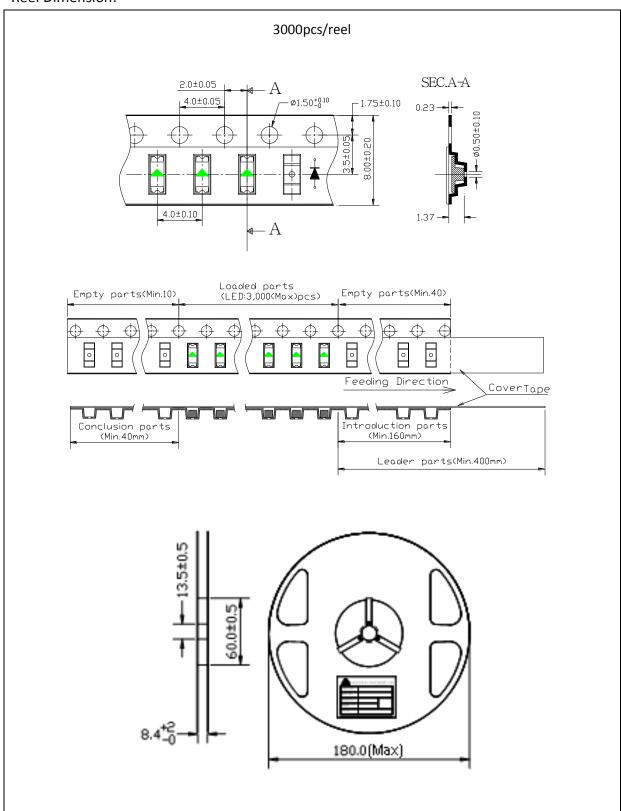
Note:

- 1. Recommend reflow temperature 245°C. Maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

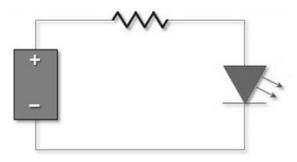
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	01/04/2016	Datasheet set-up.